

Appl. No. 10/726,945
Amdt. Dated January 23, 2006
Reply to Office Action of October 21, 2005

Amendments to the Claims:

Claim 1 (currently amended): An interconnect system comprising:

a circuit board comprising a first interface compatible with at least two signal transmission standards;

an electronic component having a second interface conforming to one of the at least two standards; and

a translation adapter interchangeable corresponding to the one of the at least two standards, the translation adapter interconnecting the circuit board and the electronic component, the translation adapter having a board-mating interface interfacing with the first interface and a component-mating interface interfacing with the second interface.

Claim 2 (original): The interconnect system as described in claim 1, wherein the circuit board comprises a plurality of electronic elements arranged thereon.

Claim 3 (original): The interconnect system as described in claim 2, wherein the circuit board defines a mating side and has a plurality of Input/Output connectors arranged along the mating side.

Claim 4 (original): The interconnect system as described in claim 1, wherein the electronic component is an electrical card.

Claim 5 (original): The interconnect system as described in claim 1, wherein the translation adapter comprises a first connector having the board-mating interface, a second connector having the component-mating interface, and a board interconnecting the first and the second connectors.

Claim 6 (original): The interconnect system as described in claim 1,

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wherein the circuit board has a plurality of golden fingers forming the first interface.

Claim 7 (original): The interconnect system as described in claim 1, wherein the circuit board has an electrical connector having the first interface therewith.

Claim 8 (original): An interconnect system assembly comprising:

a circuit board defining a base interface thereof;

first and second electronic components different from each other and respectively defining different first and second interfaces thereof;

first and second adapters different from each other, the first adapter defining a board-mating interface adapted to be mated with the base interface and a first component-mating interface opposite to said board-mating interface and adapted to be mated with the first interface, and the second adapter defining another board-mating interface similar to said board-mating interface and a second component-mating interface opposite to said another board-mating interface and adapted to be mated with the second interface, said first component-mating interface being different from said second component-mating interface; wherein

said first component along with the first adapter and said second component along with the second adapter are mutually exclusively assembled with the circuit board.

Claim 9 (new): The interconnect system assembly as described in claim 8, wherein the first electronic component is a PCI card, the second electronic component is a PCI-Express card.

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Claim 10 (new): The interconnect system assembly as described in claim 8, wherein the first electronic component is a PCI card, the second electronic component is a NewCard.

Claim 11 (new): The interconnect system assembly as described in claim 8, wherein the first electronic component is a PCI-Express card, the second electronic component is a NewCard.